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Atty. Dkt. No.: IDT-1661

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Kong Lam Song

Application No.: 09/888,363

Filing Date: 06/21/2001

For: "Die Bonding Apparatus With Automatic Die And Lead Frame Image Matching System"

Art Unit.: 2623

Examiner: Chong R. Kim

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SEP 16 2004

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Technology Center 2600

Date: September 8, 2004

AMENDMENT TRANSMITTAL

1. Transmitted herewith is an amendment for this application.
2. **STATUS:** Applicant is other than a small entity.
3. **EXTENSION OF TERM:** The proceedings herein are for a patent application and the provisions of 37 C.F.R. 1.136 apply. Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. **FEE FOR CLAIMS:** The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

	(Col.1)		(Col. 2)	(Col. 3)	LARGE ENTITY	
	Claims Remaining After Amendment		Highest No. Previously Paid For	Present Extra	Rate	Addit. Fee
Total	7	Minus	20	= 0	x \$18 =	\$0
Indep.	2	Minus	3	= 0	x \$86 =	\$0
First Presentation of Multiple Dependent Claim					+ \$290 =	\$0
Total					Addit. Fee	\$0

No additional fee for claims is required.

5. **FEE DEFICIENCY:** If any additional extension and/or fee is required, please charge Deposit Account No. 50-0574.

SIGNATURE OF PRACTITIONER

Patrick T. Bever

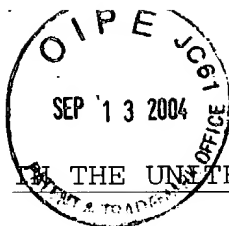
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I hereby certify that this correspondence is being deposited with the United States Postal Service as FIRST CLASS MAIL in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 8, 2004.

Date: 9/8/2004 Signature: Rebecca A. Baumann

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Kong Lam Song
Assignee: Integrated Device Technology, Inc.
Title: DIE BONDING APPARATUS WITH AUTOMATIC DIE AND LEAD
FRAME IMAGE MATCHING SYSTEM
Serial No.: 09/888,363-8897 Filing Date: June 21, 2001
Examiner: C. Kim Art Unit: 2623
Docket No.: IDT-1661

MAIL STOP AMENDMENT
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September 8, 2004

AMENDMENT IN RESPONSE TO FIRST OFFICE ACTION

In response to the Office Action dated July 8, 2004, please
amend the present application as follows.